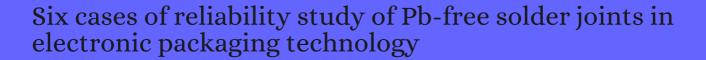
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1187	Effect of phosphorus content and solid state aging on intermetallic formation between lead-free Sn-Ag-Cu solder and electroless nickel/immersion gold under bump metallurgy.		3
1186	Growth of an intermetallic compound layer with Sn-3.5Ag-5Bi on Cu and Ni-P/Cu during aging treatment. <i>Journal of Electronic Materials</i> , 2003 , 32, 1195-1202	1.9	76
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332 331 330 329 328	Reflow Optimization Process: Thermal Stress Using Numerical Analysis and Intermetallic Spallation in Backwards Compatibility Solder Joints. 2015, 40, 1669-1679 Apparatus for electronic component disassembly from printed circuit board assembly in e-wastes. 2015, 144, 11-15 Evolution of the Intermetallic Compounds in Ni/Sn-2.5Ag/Ni Microbumps for Three-Dimensional Integrated Circuits. <i>Journal of Electronic Materials</i> , 2015, 44, 3888-3895 Differences in the interfacial reaction between Cu substrate and metastable supercooled liquid Sntu solder or solid Sntu solder at 222 tc: Experimental results versus theoretical model calculations. 2015, 99, 106-118 Growth kinetics of IMCs in Cu-Sn intermetallic joints during isothermal soldering process. 2015,		7 32 6 21 2

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